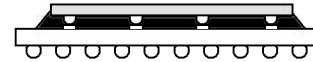


Liquid encapsulant for semiconductor

CV5300AK

TECHNICAL INFORMATION

Encapsulation Materials Group
Plastic Materials Division
Electronic Materials Business Unit
Industrial Devices Company
Panasonic Corporation



CV5300AK is one component epoxy for Flip-chip underfilling.

CV5300AK has high adhesion strength.

CV5300AK exhibits high thermal resistivity

TYPICAL PROPERTIES

Properties	Unit	Data	Test Method
Viscosity(25°C)	Pa*s	20	KES 0171
Gelation time(165°C)	sec	800	KES 0175

RECOMMENDING APPLYING CONDITION

Preheating condition Substrate : 100~120°C / 5min or more
Syringe : r.t.

Dispensing condition Substrate : 100~120°C

Curing condition 100°C/1hour + 150°C2hour

TYPICAL CURED PROPERTIES

Cure Conditions : 100°C/1hour+150°C/2hour

Properties	Unit	Data	Test Method
Glass Trans. Temp.	°C	160	KES 0109
C.T.E. (< Tg)	×10 ⁻⁵ /°C	2.5	KES 0109
C.T.E. (Tg <)	×10 ⁻⁵ /°C	8.5	KES 0109
Flexural Strength	MPa	160	JIS K6911
Flexural Modulus	GPa	9	JIS K6911
Extractable (Na ⁺)	ppm	<30	KES 0149 ^{A)}
Inpurity ion (Cl)		<30	

ATTENTION TO STORAGE

- Stored compound must be thawed before use. Warm at room temperature until no longer cool to touch (about 2hrs).
- Please use up the material within 24 hrs.
- Compound must be stored in the cool condition with sealing.
(store under -20°C in refrigerator)
- Please keep material under -20°C after receiving product.

Treatment Conditions

(A):PCT with 10% water for 20hrs
resin was cured and crushed

ATTENTION TO HANDLING

- Please avoid direct contact with this product by wearing gloves, protecting gears, etc.
- Prevent frequent skin contact. If contact occurs, wash immediately with soap and water.

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